



## PATENT ABSTRACTS OF JAPAN

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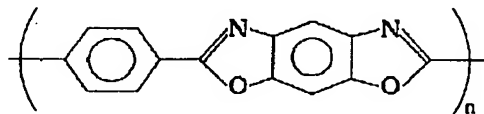
(54) **METHOD FOR TREATING**  
**POLYPARAPHENYLENEBENZOBISOXAZOLE**  
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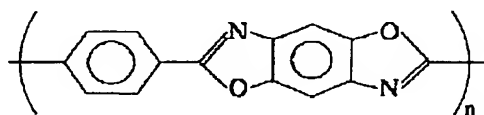
(57) Abstract:

**PURPOSE:** To improve adhesion to rubber by bonding a specific polyoxy compound to polyparaphenylene benzobisoxazole (PBO) fiber surface and then bonding a RFL aqueous solution having a specific molar ratio thereto.

**CONSTITUTION:** A polyepoxy compound having 0.01-0.5wt.% two or more epoxy groups in the molecule is subjected to reactive bonding to the surface of high-strength and high-modulus PBO fiber consisting of recurring units of a monomer of formula I or formula II [*n* is recurring number] and a RFL aqueous solution in which a molar ratio *F* of formaldehyde to resorcin is expressed by the formula  $1.2 \leq F \leq 2.4$  and a solid content ratio *L* of rubber latex aqueous solution to RF condensation product obtained by reacting in the presence of an alkali catalyst is expressed by the formula  $5 \leq L \leq 10$  is bonded thereto and the surface is thermally treated at  $\approx 100^\circ\text{C}$  to improve adhesion to rubber.



I



II